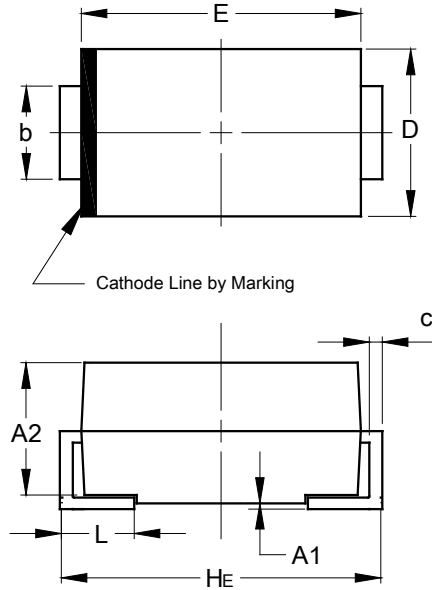


Package Outline Dimensions

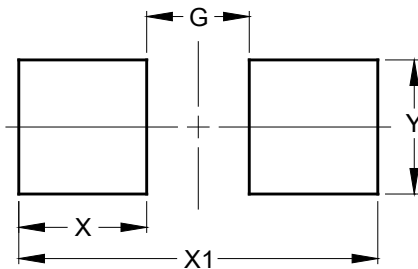
DO-214AC



DO-214AC		
Dim	Min	Max
A1	0.080	0.310
A2	1.900	2.290
b	1.250	1.650
c	0.150	0.310
D	2.400	2.830
E	3.990	4.750
H _E	4.800	5.280
L	0.760	1.520
All Dimensions in mm		

Suggested Pad Layout

DO-214AC



Dimensions	Value (in mm)
G	1.600
X	2.000
X1	5.600
Y	2.100

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.